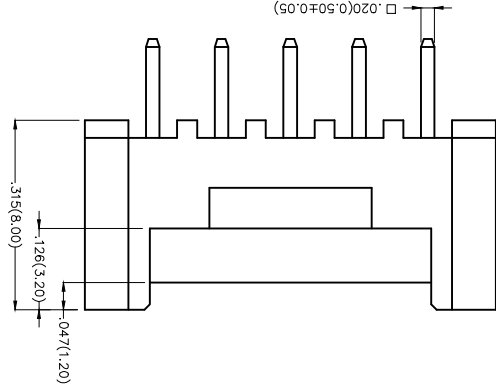
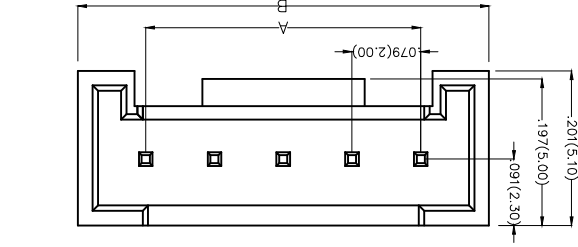


Ordering Information

Electrical
Current Rating: 2.0A AC(rms)/DC
Voltage Rating: 125V AC(rms)/DC
Contact Resistance: 20 mΩ Max
Insulation Resistance: 1000 MΩ MIN
Withstanding Voltage: 1000V AC r.m.s
Temperature Range—Operating: -25°C~+85°C
Material and Plating
Housing: PA66 (UL 94V-2)
Contact Pin: Brass
Plating: Tin Plated

1	Category	FWF—Wafer	
		2	Series Number
2		200—Pitch 2.0mm	
		3	Distinction No.
3		09	
		4	Row Option
4		S—Single Row	
		5	Circuits
5		XX	
		6	Entry Angle
6		S—180° Vertical	
		7	Packaging
7		B—PE Bag	
		8	Material—Resin
8		2—PA66	
		9	Color—Resin
9		W1—White	
		10	W5—White
10		2—Tin Plated	
		11	Plating

FWF 200 09 — S XX S 2 2 XX B

THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	GENERAL TOLERANCES (UNLESS SPECIFIED)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.±.012(0.30)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.006(0.15)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.004(0.10)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.015(0.38)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.±.012(0.30)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.020(0.51)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.±.012(0.30)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.025(0.64)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.031(0.80)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.004(0.10)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.035(0.90)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.043(1.10)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.047(1.20)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.059(1.50)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.063(1.60)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.079(2.00)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.083(2.10)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.091(2.30)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.095(2.40)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.106(2.70)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.110(2.80)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.118(3.00)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.122(3.10)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.126(3.20)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.134(3.40)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.138(3.50)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.146(3.70)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.150(3.80)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.157(4.00)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.161(4.10)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.169(4.30)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.173(4.40)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.177(4.50)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.181(4.60)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.185(4.70)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.189(4.80)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.193(4.90)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.197(5.00)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.201(5.10)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.205(5.20)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.209(5.30)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.213(5.40)		DATE 18/JUN/13	CHECKED BY FRANK	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE 5:1	SIZE A4	X.XX±.217(5.50)		DATE 18/JUN/13	CHECKED BY JACOB	DATE 18/JUN/13	PART NO. FWF20009-SXXS22XXB	ITEM NO. FWF20009	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (DIP)	REV 0	SHEET NO. 1/2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
				X.XX±.006(0.15)										
THIRD ANGLE PROJECTION	DESIGN UNITS Inch (metric)	SCALE												

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF20009-S02S22XXB	.079(2.00)	.236(6.00)
3	FWF20009-S03S22XXB	.157(4.00)	.315(8.00)
4	FWF20009-S04S22XXB	.236(6.00)	.394(10.00)
5	FWF20009-S05S22XXB	.315(8.00)	.472(12.00)
6	FWF20009-S06S22XXB	.394(10.00)	.551(14.00)
7	FWF20009-S07S22XXB	.472(12.00)	.630(16.00)
8	FWF20009-S08S22XXB	.551(14.00)	.709(18.00)
9	FWF20009-S09S22XXB	.630(16.00)	.787(20.00)
10	FWF20009-S10S22XXB	.709(18.00)	.866(22.00)
11	FWF20009-S11S22XXB	.787(20.00)	.945(24.00)
12	FWF20009-S12S22XXB	.866(22.00)	1.024(26.00)

 THIRD ANGLE PROJECTION		DESIGN UNITS Inch (metric)		SCALE SIZE A4		4															
						5															
						6															
DATE 18/JUN/13		APPROVE BY FRANK		DATE 18/JUN/13		CHECKED BY JACOB		DRAWN BY CHERRY		DATE 18/JUN/13		PART NO. FWF20009-SXXS22XXB		ITEM NO. FWF20009		TXGA Leader Of Industry		REV 0 SHEET NO. 2/2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(SZ)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
DATE 18/JUN/13		DATE 18/JUN/13		DATE 18/JUN/13		DATE 18/JUN/13		DATE 18/JUN/13													
DATE 18/JUN/13		DATE 18/JUN/13		DATE 18/JUN/13		DATE 18/JUN/13		DATE 18/JUN/13		DATE 18/JUN/13											

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